505677631 09/18/2019

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JONATHAN ALMERIA NOQUIL	09/10/2019
MAKARAND RAMKRISHNA KULKARNI	09/10/2019

RECEIVING PARTY DATA

Name:	TEXAS INSTRUMENTS INCORPORATED	
Street Address:	12500 TI BOULEVARD	
Internal Address:	M/S 3999	
City:	DALLAS	
State/Country:	TEXAS	
Postal Code:	75243	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16574226

CORRESPONDENCE DATA

Fax Number: (214)567-2228

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided: if that is unsuccessful, it will be sent via US Mail.

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 214-479-1230 Email: uspto@ti.com

Correspondent Name: TEXAS INSTRUMENTS INCORPORATED

Address Line 1: P O BOX 655474, M/S 3999
Address Line 4: DALLAS, TEXAS 75265

ATTORNEY DOCKET NUMBER:	TI-90825
NAME OF SUBMITTER:	NEIL R. JETTER
SIGNATURE:	/Neil R. Jetter/
DATE SIGNED:	09/18/2019

Total Attachments: 2

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PATENT 505677631 REEL: 050411 FRAME: 0758

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made.

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefore, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year,

TITLE OF INVENTION	STACKED DIE MULTICHIP MODULE PACKAGE
SIGNATURE OF INVENTOR AND NAME	= XXVI-PVIII L Jonathan Almeria Noquii
DATE	09-10~ M
RESIDENCE (CITY AND STATE)	Piano, TX

TITLE OF INVENTION	STACKED DIE MULTICHIP MODULE PACKAGE
SIGNATURE OF INVENTOR AND NAME	Mallarand Ramkrishna Kulkarni
DATE	9/10/2019
RESIDENCE (CITY AND STATE)	Dallas, TX

After recording, return Assignment to:

Texas Instruments Incorporated PO Box 655474, M/S 3999 Dallas, TX 75265

PATENT REEL: 050411 FRAME: 0760